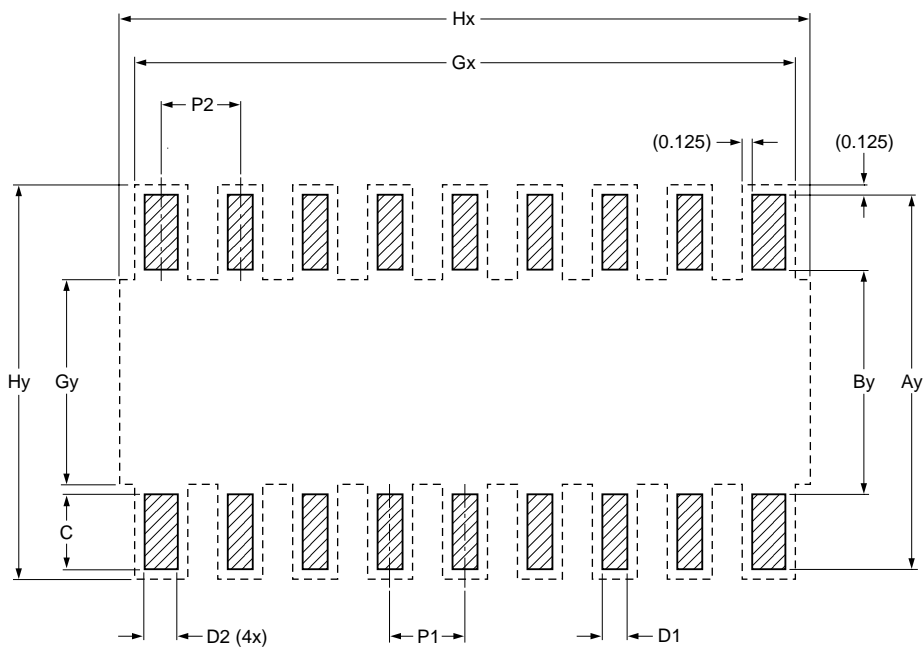


Footprint information for reflow soldering of TSSOP14 package

SOT402-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

- solder land
- occupied area

DIMENSIONS in mm

| P1 | P2 | Ay | By | C | D1 | D2 | Gx | Gy | Hx | Hy |
|-------|-------|-------|-------|-------|-------|-------|-------|-------|-------|-------|
| 0.650 | 0.750 | 7.200 | 4.500 | 1.350 | 0.400 | 0.600 | 4.950 | 5.300 | 5.800 | 7.450 |